IPC ASSOCIATION ELECTRONIC	Material Compo © Copyright 2005. IP SINDUSTRIES® international and Pan-	C, Bannockb	urn, Illinois. A	All rights reserved un	nder both	This docume level parts, t	ent is a declar he declaration	ation of the encomp	he substances asses all lowe	within the	e manufactur terials for w	rer listed ite hich the m	em. Note: i anufacture	if the item is an as r has engineering	sembly with lowe responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplie	r Information														
Company name* Comp				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2025-07-04			
Contact N	lame	Title - Contact				Phone - Contact*				Email - Contact*					
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ate Version Manufacturing Site		iring Site	Weight*		UOM	Unit Type	
		NTPF165	NTPF165N65S3H Suj		SuperFET3 FAST, 165mohm, TO-220F		2025-07-04			СРА		2	038.97	mg	Each
Manufa	cturing Proccess Informati	ion		'			1							1	1
	Terminal Plating / Grid Array Material T		Cerminal Base Alloy J-STD-020 M		-STD-020 MSL	Rating	Peak Process Body Temperat		ture Max Time at Peak Temper		Temperatu	ire Numb	ber of Reflow Cyc	eles	
	Matte Tin (Sn) - annealed		CU Alloy NA		VA.		<b>0</b> C		30 seco		secono	ds 3			
Comments	3														
or more	information regarding material c	omposition ]	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.74	mg	Supplier	Silicon (Si)	7440-21-3		5.74	mg
Die Attach	4.04	mg	Supplier	Silver (Ag)	7440-22-4		0.0606	mg
			A	Lead (Pb)	7439-92-1	7a	3.7774	mg
			Supplier	Tin (Sn)	7440-31-5		0.202	mg
Lead Frame	1492.12		Supplier	Iron (Fe)	7439-89-6		1.3429	mg
			Supplier	Copper (Cu)	7440-50-8		1490.3295	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4476	mg
Mold Compound-Black	521.33			Phenolic Resin	proprietary data		26.0665	mg
			Supplier	Carbon Black (C)	1333-86-4		2.6067	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		28.6732	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		36.4931	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		36.4931	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		390.9975	mg
Plating	13.3	mg	Supplier	Tin (Sn)	7440-31-5		13.3	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg